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|--------------------------|-----------------|--------------------------|---|
| 文件编号<br>Document No.     | ESP-07-2-007-03 | 文件名称<br>Document Name    | 产品/工艺变更通知<br>Product/Process Change Notice<br>(PCN) |
| 文件版本<br>Document Version | 1.3             | 保存期限<br>Retention Period | 5 年<br>5 years                                      |

**ESP32-C3 系列产品的芯片版本由版本 3 升级为版本 4**

**Upgrade Chip Revision of ESP32-C3 Series Products from Chip Revision 3 to Chip Revision 4**

|                                 |  |   |            |
|---------------------------------|--|---|------------|
| PCN 编号<br>PCN No.               | PCN20220101  | 提出日期<br>Issue Date of PCN                 | 2022/03/30 |
| 变更日期<br>Proposed Date of Change | 2022/04/30   | 首次出货日期<br>Proposed Date of First Shipment | 2022/06/15 |
| PCN 类型 / PCN Category           | <input type="checkbox"/> 客户需要批准/ Customer Approval Required<br><input checked="" type="checkbox"/> 客户通知/ Customer Notification |   |            |

**1. 影响产品名称/ Affected Product Name**

1) 芯片产品信息/ Chip Products Information:

ESP32-C3, ESP32-C3FN4, ESP32-C3FH4, ESP8685H2, ESP8685H4  
 ESP32-C3FN4AZ, ESP32-C3FH4AZ

2) 模组产品信息/ Module Products Information:

| Product Name       | Product MPN           |
|--------------------|-----------------------|
| ESP8685-WROOM-01   | ESP8685-WROOM-01-H2   |
|                    | ESP8685-WROOM-01-H4   |
| ESP8685-WROOM-03   | ESP8685-WROOM-03-H2   |
|                    | ESP8685-WROOM-03-N2   |
|                    | ESP8685-WROOM-03-H4   |
| ESP8685-WROOM-04   | ESP8685-WROOM-04-H2   |
|                    | ESP8685-WROOM-04-H4   |
| ESP8685-WROOM-05   | ESP8685-WROOM-05-H2   |
|                    | ESP8685-WROOM-05-H4   |
| ESP8685-WROOM-06   | ESP8685-WROOM-06-H2   |
|                    | ESP8685-WROOM-06-H4   |
| ESP8685-WROOM-07   | ESP8685-WROOM-07-H2   |
|                    | ESP8685-WROOM-07-H4   |
| ESP32-C3-WROOM-02  | ESP32-C3-WROOM-02-N4  |
|                    | ESP32-C3-WROOM-02-H4  |
| ESP32-C3-WROOM-02U | ESP32-C3-WROOM-02U-N4 |
|                    | ESP32-C3-WROOM-02U-H4 |
| ESP32-C3-MINI-1    | ESP32-C3-MINI-1-N4    |
|                    | ESP32-C3-MINI-1-H4    |
| ESP32-C3-MINI-1U   | ESP32-C3-MINI-1U-N4   |
|                    | ESP32-C3-MINI-1U-H4   |
| ESP32-C3F5V1       | ESP32-C3F5V1          |
| ESP32-C3-WIZ2012   | ESP32-C3-WIZ2012      |

### 3) 开发板产品信息/ Development Board Products Information:

| Product Name                    | Product MPN                     |
|---------------------------------|---------------------------------|
| ESP32-C3-DevKitM-1              | ESP32-C3-DevKitM-1              |
|                                 | ESP32-C3-DevKitM-1U             |
| ESP32-C3-DevKitC-02             | ESP32-C3-DevKitC-02             |
|                                 | ESP32-C3-DevKitC-02U            |
| ESP32-C3-nami                   | ESP32-C3-MINI-1-N4-NAMI         |
| ESP32-C3-AWS-Expresslink-DevKit | ESP32-C3-AWS-Expresslink-DevKit |
| ESP32-C3-WIZ2016                | ESP32-C3-WIZ2016                |
| ESP32-C3-Adaptor-ANV            | ESP32-C3-Adaptor-ANV-H4         |

### 2. 变更原因/ Reason for Change

为提升 ESP32-C3 系列芯片的生产效率，对 ESP32-C3 系列芯片进行优化。

段落 1 中列出的模组和开发板产品的主芯片为 ESP32-C3 系列芯片，因此相应地发生变更。

Internal optimization of ESP32-C3 series chip to improve the production capacity of ESP32-C3 series chip products. Modules and development board products listed in Para 1 are based on ESP32-C3 series of chips, and thus will change accordingly.

### 3. 变更描述/ Description of Change

段落 1 中列出的产品为 ESP32-C3 系列产品，其所含的主芯片的芯片版本由版本 3 升级为版本 4。

Upgrade the main chip revision of ESP32-C3 series products listed in Para 1 from chip revision 3 to chip revision 4.

### 4. 变更对比/ Change Comparison

请见附录 I: 变更对比。

Please refer to Appendix I: Change comparison.

识别方式/ Identification Method:

芯片产品通过 eFuse 及产品丝印。

Chip products: Identified by eFuse bits and chip marking.

模组产品通过丝印中的产品规格标识位识别。

Module products: Identified by module marking.

### 5. 变更影响/ Impact of Change

1) 品质和性能/ Quality & Performance: 无影响/ No impact

2) 交期/ Delivery: 无影响/ No impact

3) 生产料号/ Material Part Numbers (MPN):

客户可以继续使用原有的芯片产品名称下单；

Customers can continue using the existing chip product name to place orders.

段落 1 中列出的模组及开发板产品的 MPN 不变更，客户可以继续使用原有的模组及开发板产品 MPN 进行下单。

There is no change to the MPN of the affected Espressif modules & development board products listed in Para 1. Customers can continue to use existing MPN to place orders.

4) 认证/ Certification: 无影响/ No impact

5) 软件/ IDF:

当前的乐鑫 IDF 版本兼容段落 1 列出的变更后的产品, 客户可继续使用现有的软件版本进行变更后产品的生产。

Changed products listed in Para 1 are compatible with the current version of ESP-IDF. Customers can still use the current version.

6. 变更前后产品处理/ How to Deal with Products

FIFO

7. 相关报告/ Report(s) Attached:

|   |              |
|---|--------------|
| <input checked="" type="checkbox"/> Related ECN No. | ECN-2022-001 |
|---|--------------|

|  |
|--|
| <input checked="" type="checkbox"/> 射频性能验证/ RF Performance Verification: <b>Pass</b> |
|--|

### Appendix I 变更对比/ Change Comparison

| No. | 项目/ Item   | 变更前/ Before Change | 变更后/ After Change |
|-----|--|--------------------|-------------------|
| 1   | ESP32-C3 Series Product Chip Revision              | 3                  | 4                 |
| 2   | ESP32-C3 Series Product Chip eFuse (BLK1 B14[4:2]) | 3                  | 4                 |
| 3   | ESP32-C3 Series Chip Product Chip Marking          |                    |                   |
|     |  | xDXXXXXX           | xEXXXXXX          |
| 4   | ESP32-C3 Series Module Product Module MPN          | No change          |                   |
| 5   | ESP32-C3 Series Module Product Module Marking      |                    |                   |
|     |  | XXXXXX             | M4XXXX            |